the alignment marks of the substrate A are observed by the camera 130. Page 16, Lines 12 – 17 then reveals that the x-y guide 116 and the motor 128 are moved so that the positions of the alignment marks of the integrated mask 1 and the positions of the alignment marks of the substrate A are made the same. Finally, Page 28, Lines 18 – 22 reveals that the relative position between the glass substrate and the integrated mask 1 is adjusted such that the alignment marks of the glass substrate and the alignment marks of the base plate of the integrated mask 1 are at the same position. The Applicants respectfully submit that this overall disclosure by JP '474 fully supports the specific language mentioned above with respect to Claim 1.

Similar comparisons are included for all of the claim language and the locations in JP '474 where corresponding support may be found. The Applicants respectfully request that the Examiner carefully consider the enclosed comparison so that confirmation of the full support of the JP '474 priority document can be confirmed. In any event, the Applicants respectfully submit that JP '474 fully does support the claims and Clark is not prior art. Withdrawal of the rejection is respectfully requested.

Claim 12 stands rejected under 35 U.S.C. §103 over the combination of Yamada with Shigeo and Clark. In that regard, the Applicants note the Examiner's helpful comments, particularly with respect to m and k satisfying the equation and equals m x k, where k is the number of the array deposition apertures.

The rejection relies in particular on the idea that "A device "n" is interpreted to be the array of pixels formed on an array of deposition apertures." The Applicants respectfully submit that this is in error. This is particularly true since the Applicants have defined the meaning of "n." In particular, the Applicants have defined "n" in Claim 11 in Paragraph (b) as the numbers of the organic EL devices on the single substrate where an n is an integer ≥ 2.

The Applicants, therefore, respectfully submit that it is impossible for the rejection to define "n" in a way that is different from the definition specifically recited in the Applicants' Claim 11.

There is no specific rejection of Claim 13 in the Official Action. However, there are comments directed to Claim 13 at the bottom of Page 3 of the Official Action. Inasmuch as Claim 13 has been cancelled, the Applicants will refrain from further commentary on that claim.

In light of the foregoing, the Applicants respectfully submit that the entire application is now in condition for allowance, which is respectfully requested.

Respectfully submitted,

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Comparison between the elements in Claims 11 and 14 and the disclosures in JP '474

Claim 11	**JP 2001-23474**
An organic EL device manufacturing method	- *Page 7, lines 9-10:* An organic EL device manufacturing method according to the present invention
comprising the steps of:	- *Page 7, line 10:* includes the steps of
(a) positioning an integrated mask and a single substrate to be subjected to a deposition process in a deposition chamber	- *Page 7, lines 10-12:* positioning the integrated mask of the present invention and a substrate to be subjected to a deposition process in a deposition chamber; and - *Page 9, lines 13-16:* In addition, since multiple organic EL devices can be formed on a single substrate at high pattern accuracy, high quality organic EL devices can be manufactured with high productivity.
using alignment marks formed on said integrated mask and said single substrate,	- *Page 15, lines 22-26:* First, the integrated mask 1 is placed on the mask holder 112 in the vacuum chamber 132, and is fixed. Then, the alignment marks 6 of the integrated mask 1 are observed by the camera 130, and the positions thereof are determined and memorized by an image processing unit (not shown). - *Page 16, lines 8-11:* Then, the elevation shaft 126 is moved downward and the substrate A is placed on the integrated mask 1, and the alignment marks of the substrate A are observed by the

	camera 130 through the looking glass 104. - *Page 16, lines 12-17:* Then, the elevation shaft 126 is moved upward until the substrate A comes away from the integrated mask 1, and the X-Y guide 116 and the motor 128 are moved and rotated by predetermined amounts so that the positions of the alignment marks of the integrated mask 1 and the positions of the alignment marks of the substrate A are made the same. - *Page 28, lines 18-22:* Accordingly, the relative position between the glass substrate and the integrated mask 1 was adjusted such that the alignment marks of the glass substrate and the alignment marks of the base plate of the integrated mask 1 were at the same positions.
wherein said integrated mask comprises: (a-1) a plurality of deposition masks each of which has an array of deposition apertures formed in accordance with a deposition pattern and alignment marks,	- *Page 6, lines 16-19:* An integrated mask according to the present invention includes a plurality of deposition masks, each deposition mask having an array of deposition apertures formed in accordance with a deposition pattern - *Page 11, lines 8-9:* the mask plates 22 of the deposition masks 20 are preferably provided with alignment marks 26
(a-2) a base plate which has a plurality openings on which said deposition masks are arranged respectively, each of said deposition masks being arranged	- *Page 6, lines 19-20:* and a base plate having a plurality of openings. - *Page 6, lines 20-22:* The deposition masks are arranged on

over respective opening, and which has alignment marks,	the base plate such that the arrays of deposition apertures are positioned above the respective openings - *Page 6, lines 24-26:* and alignment marks used for positioning the deposition masks on the base plate are formed on the base plate.
(a-3) a plurality of engaging units provided on said base plate that engage and disengage each of said deposition masks such that the position of each deposition mask is adjusted relative to the base plate independently of the other deposition masks, and	- *Page 6, lines 20-24:* The deposition masks --- are retained to the base plate by engaging means in a disengageable manner - *Page 12, lines 8-17:* Accordingly, the pressing force applied to the deposition masks 20 against the base plate 2 is removed, and the deposition masks 20 are able to move over the base plate 2. The deposition masks 20 are positioned relative to the base plate 2 while the retaining force is removed in this manner. When the positioning process is completed, the upward pressing force applied to the catches 46 is removed, so that the deposition masks 20 are retained by being pressed against the base plate 2 by the spring force of the engaging units 40.
wherein said integrated mask is fabricated by the steps of: (a-4) detecting said alignment marks of said base plate and each of said deposition masks,	- *Page 10, line 26 - page 11, line 11:* Each of the deposition masks 20 is positioned on the base plate 2 such that the deposition apertures 32 are at predetermined positions by using alignment marks 6 formed on the top surface of a projecting member 4 of the base

	plate 2 as the reference. The positions of the deposition apertures 32 may be directly detected and the deposition masks 20 may be positioned relative to the alignment marks 6 on the base plate 2 on the basis of the detection result. However, the mask plates 22 of the deposition masks 20 are preferably provided with alignment marks 26, and the positions of the alignment marks 26 are preferably adjusted relative to the alignment marks 6 on the base plate 2.
(a-5) adjusting the relative position between said base plate and each of said deposition masks prior to engaging the integrated mask with the substrate by independently retaining and independently moving each of said deposition masks relative to said base plate, and	- *Page 12, lines 8-17:* Accordingly, the pressing force applied to the deposition masks 20 against the base plate 2 is removed, and the deposition masks 20 are able to move over the base plate 2. The deposition masks 20 are positioned relative to the base plate 2 while the retaining force is removed in this manner. When the positioning process is completed, the upward pressing force applied to the catches 46 is removed, so that the deposition masks 20 are retained by being pressed against the base plate 2 by the spring force of the engaging units 40.
(a-6) retaining each of said deposition masks on said base plate using said engaging units after adjusting of said relative position; and	- *Page 12, lines 13-17:* When the positioning process is completed, the upward pressing force applied to the catches 46 is removed, so that the deposition masks 20 are retained by being pressed against the

	base plate 2 by the spring force of the engaging units 40.
(b) patterning a thin film layer in said deposition process using said integrated mask, thereby forming n said organic EL devices on said single substrate wherein n is an integer equal to or greater than 2.	- *Page 7, lines 11-16:* a substrate to be subjected to a deposition process in a deposition chamber based on the alignment marks of the integrated mask and patterning a thin film layer in the deposition process using the integrated mask, thereby forming a plurality of organic EL devices.
Claim 14	**JP 2001-23474**
An organic EL device manufacturing method according to claim 11, wherein said thin film is an emitting layer or a metal electrode layer.	- *Page 25, line 14 - page 26, line 4:* This integrated mask 1 was used for forming a green emitting layer ---. Then, an integrated mask for forming a red emitting layer ---. In addition, an integrated mask for forming a blue emitting layer ---. Thus, preparation for depositing all of the green, red, and blue emitting layers was completed. - *Page 32, lines 6-9:* In addition, although the mask deposition method was also used in the process of forming the second electrodes, the metal electrodes may also be formed without using the deposition mask.